

#### Silicon TVS diodes Array

 ESD / transient protection of e.g. ADSL, VDSL, ISDN, WAN, LAN, I<sup>2</sup>C Bus, Microcontroller Inputs, Video and other high-speed data lines in telecom applications:

IEC61000-4-2 (ESD):  $\pm$  15 kV (Air / Contact) IEC61000-4-4 (EFT): 4 kV / 80 A (5/50 ns) IEC61000-4-5 (Lightning): 27 A (8/20  $\mu$ s)

- Very low capacitance
- Extremly low reverse current < 5 nA
- Pb-free (RoHS compliant) package



#### **DSL70**

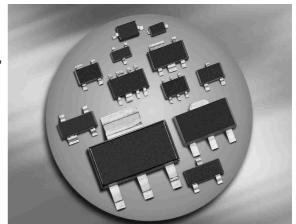


Туре	Package	Configuration	Marking	
DSI 70	SOT143	2 channel rail to rail	F4s	

#### **Maximum Ratings** at $T_A = 25$ °C, unless otherwise specified

Parameter	Symbol	Value	Unit
ESD contact discharge per diode <sup>1)</sup>	V <sub>ESD</sub>	15	kV
Peak pulse current $(t_p = 8 / 20 \mu s)^2$	I <sub>pp</sub>	27	А
Peak pulse power ( $t_p$ = 8 / 20 $\mu$ s)	$P_{pk}$	245	W
Operating temperature range	$T_{op}$	-55125	°C
Storage temperature	T <sub>stg</sub>	-65150	

 $<sup>^{1}</sup>V_{\text{ESD}}$  according to IEC61000-4-2



 $<sup>^2</sup>I_{\rm pp}$  according to IEC61000-4-5



# **Electrical Characteristics** at $T_A = 25$ °C, unless otherwise specified

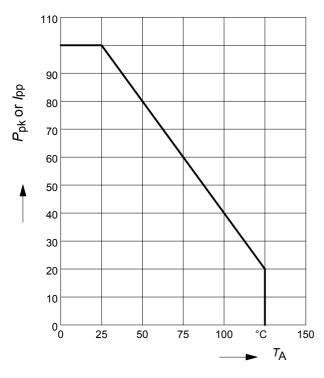
Parameter	Symbol	Values		Unit	
		min.	typ.	max.	
Characteristics -	·				
Reverse working voltage	$V_{RWM}$	-	-	50	V
Reverse current	I <sub>R</sub>	-	-	5	nA
$V_{R} = 50 \text{ V}$					
Forward clamping voltage <sup>1)</sup>	V <sub>FC</sub>				V
$I_{PP} = 1 \text{ A}, t_{P} = 8/20  \mu\text{s}$		-	1	1.5	
$I_{PP}$ = 10 A, $t_{P}$ = 8/20 µs		-	2.5	3	
$I_{PP} = 24 \text{ A}, t_{P} = 8/20  \mu\text{s}$		-	5	6	
$I_{PP} = 27 \text{ A}, t_{P} = 8/20  \mu\text{s}$		-	6	9	
Diode capacitance	C <sub>T</sub>				pF
$V_{R}$ = 0 V, $f$ = 1 MHz, between I/0 and GND		-	2.5	5	
$V_R = 0 \text{ V}, f = 1 \text{ MHz}, \text{ between I/0 pins}$		_	1.25	2.5	

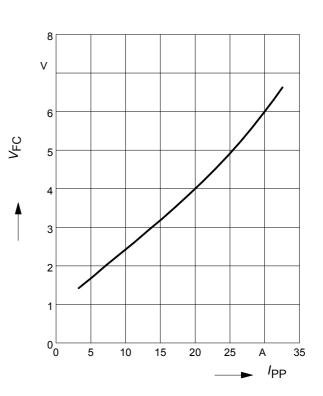
 $<sup>^{1}</sup>I_{\mathrm{PP}}$  according to IEC61000-4-5



## Power derating curve $P_{pk} = f(T_A)$

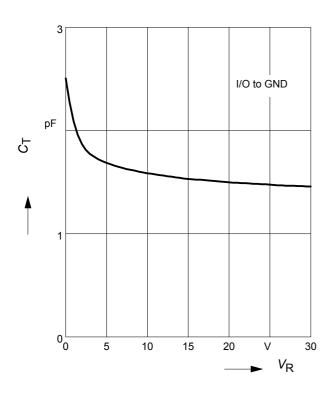
# Forward clamping voltage $V_{FC}$ = $f(I_{PP})$ $t_p$ = 8 / 20 µs





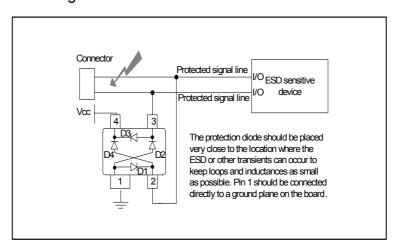
## Diode capacitance $C_T = f(V_R)$

f = 1MHz



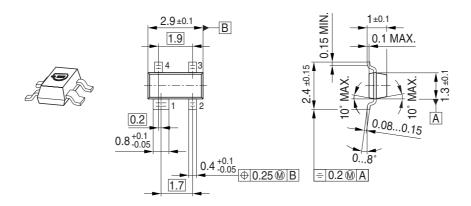


# **Application example** DSL70 dual channel, rail to rail configuration

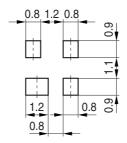




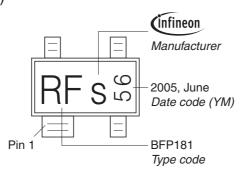
#### Package Outline



#### Foot Print

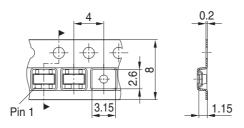


#### Marking Layout (Example)



#### Standard Packing

Reel ø180 mm = 3.000 Pieces/Reel Reel ø330 mm = 10.000 Pieces/Reel





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